				Time chame
L Number	Hits	Search Text	DB	Time stamp
- Number	89	(73/504.04).CCLS.	USPAT;	2002/09/12
	03	(13/304/6-1/-0-2-1	US-PGPUB	17:15
İ	300	(73/504.12).CCLS.	USPAT;	2002/09/10
-	300	(73/304.12).00201	US-PGPUB	17:41
	27	((73/504.12).CCLS.) and resin	USPAT;	2002/09/10
-	21	((73/304.12):00201) and 10011	US-PGPUB	17:43
-	512	73/514.32	USPAT;	2002/09/12
	512	13/514.32	US-PGPUB	18:19
	070	73/514.01	USPAT;	2002/09/12
-	270	73/514.01	US-PGPUB	17:22
		73/514.32 and integrated near2 chip	USPAT;	2002/09/12
-	23	73/514.32 and integrated hear comp	US-PGPUB	18:24
		(73/514.32 and integrated near2 chip) and	USPAT;	2002/09/12
-	4	1 .	US-PGPUB	18:22
		resin	USPAT;	2002/09/12
•	13	73/514.01 and integrated near2 chip	US-PGPUB	18:25
		see that went about ohin) and	USPAT;	2002/09/12
-	2	(73/514.01 and integrated near2 chip) and	US-PGPUB	18:26
		resin	USPAT;	2002/09/12
•	43539	thermoplastic near2 resin	US-PGPUB	18:27
			USPAT;	2002/09/13
-	24	(thermoplastic near2 resin) and	US-PGPUB	09:50
		acceleration near2 sensor		2002/09/13
-	9	(thermoplastic near2 resin) and gyro	USPAT; US-PGPUB	10:09
-			i	2002/09/13
•	15	(thermosetting near2 resin) and gyro	USPAT;	10:21
			US-PGPUB	2002/09/13
•	33806	semiconductor near2 chip	USPAT;	
			US-PGPUB	10:22
-	304	semiconductor near2 sensor near2 chip	USPAT;	2002/09/13
			US-PGPUB	10:22
-	262		USPAT;	2002/09/13
		(semiconductor near2 sensor near2 chip)	US-PGPUB	10:24
_	52	((semiconductor near2 chip) and	USPAT;	2002/09/13
		(semiconductor near2 sensor near2 chip))	US-PGPUB	10:47
		and acceleration		
_	5	0 - 1:>	USPAT;	2002/09/13
-		(semiconductor near2 sensor near2 chip))	US-PGPUB	11:27
		and acceleration) and thermoplastic		
	5		USPAT;	2002/09/13
-		(semiconductor near2 sensor near2 chip))	US-PGPUB	11:28
		and acceleration) and thermoplastic) and		
		acceleration		